**Features**

1. Small and low profile type 2P wire to board ID method connector of 0.75mm cable pitch and 0.9mm mating height.
2. Resistant to vibration and shocks when dropped and highly reliable due to a 2point contact structure.
3. Cable connection helping to achieve excellent cable retention performance and contact reliability due to double insulation displacement slots at the front and back.
4. A top entry mating structure where the wire emerges horizontally.
5. Excellent mating retention force in addition to ensured clicking feeling during insertion and withdrawal due to the mold locking structure.

**Specification**

1. Cable pitch : 0.75 mm
2. Rating : 1A, 30V AC/DC
3. Contact Resistance : 20mΩ max., initially
4. Insulation Resistance: 100MΩ min. at 250V DC
5. Withstanding Voltage : 250V AC (for one minute)
6. Operating Temperature Range : –25°C to +85°C
7. Applicable Cable : AWG32, 0.39mm Dia. jacket OD
ID-02 Series

**Material and Plating**
- **Receptacle**: CFX3102-0201F
  - Housing: Thermoplastic Resin, Black, 94HB
  - Contact: Cu Alloy, Au Plating

**Plug**: CFX3302-0201F

**Material and Plating**
- **Housing**: Thermoplastic Resin, White, 94V-0
- **Contact**: Cu Alloy, Au Plating